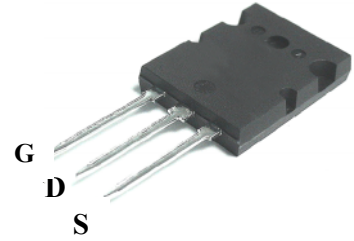
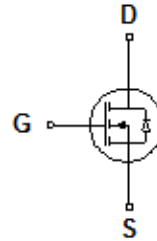


PRELIMINARY DATASHEET
**900V 2X36A N-Channel CoolMOS™ Parallel
 In TO264 Package**

- Extreme dv/dt rated
- High peak current capability
- Ultra low gate charge
- Designed for
 - Industrial SMPS
 - Consumer applications
 - Quasi resonant flyback / forward topologies
- Pb-free lead finish; RoHS compliant


MAXIMUM RATINGS, $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Units
Drain - Source Voltage	V_{DSS}	900	V
Drain current – continuous $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_D	72 46	A
Drain current – pulsed ¹	$I_{D,pulse}$	192	
Continuous diode forward current	I_S	52	
Diode pulse current ¹	$I_{S,pulse}$	162	
Avalanche current ^{1,2}	I_{AR}	8.8	
Single-pulsed avalanche energy $I_D = 8.8\text{A}$, $V_{DD} = 50\text{V}$	E_{AS}	1940	mJ
Repetitive avalanche energy ^{1,2} $I_D = 8.8\text{A}$, $V_{DD} = 50\text{V}$	E_{AR}	2.9	
Peak diode recovery	dv/dt	50	V/ns
Gate source voltage Static AC ($f > 1\text{Hz}$)	V_{GS}	± 20 ± 30	
Operating junction and storage temperature	T_j, T_{stg}	-55... +150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Max. Value	Units
Characteristics			
Thermal resistance, junction to case	R_{thJC}	0.15	K/W
Thermal resistance, junction to ambient	R_{thJA}	62	

ELECTRICAL CHARACTERISTICS, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 500\mu A$	900	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 5.8mA$	2.5	3.0	3.5	
Zero gate voltage drain current	I_{DSS}	$V_{GS} = 0V, V_{DS} = 900V$ $T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$	- -	- 100	20 -	μA
Gate-body leakage current, forward	I_{GSS}	$V_{GS} = 20V, V_{DS} = 0V$	-	-	200	nA
Static drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 52A$ $T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$	- -	0.05 0.135	0.06 -	Ω
Gate resistance	R_G	$f = 1MHz, \text{open drain}$	-	0.9	-	
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{DS} = 25V,$ $V_{GS} = 0V,$	-	13600		pF
Output capacitance	C_{oss}	$f = 1MHz$	-	660		

SWITCHING CHARACTERISTICS

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Turn-on delay time	$t_{d(on)}$	$V_{DS}=400V, V_{GS} = 10V$ $I_D=52A, R_G=3.65\Omega$	-	70	-	ns
Rise time	t_r		-	20	-	
Turn-off delay time	$t_{d(off)}$		-	400	-	
Fall time	t_f		-	25	-	
Gate charge	Q_g	$V_{DS} = 400V, I_D = 52A$ $V_{GS} = 0V \text{ to } 10V$	-	540	-	nC
Gate-source charge	Q_{gs}		-	64	-	
Gate-drain charge	Q_{gd}		-	230	-	

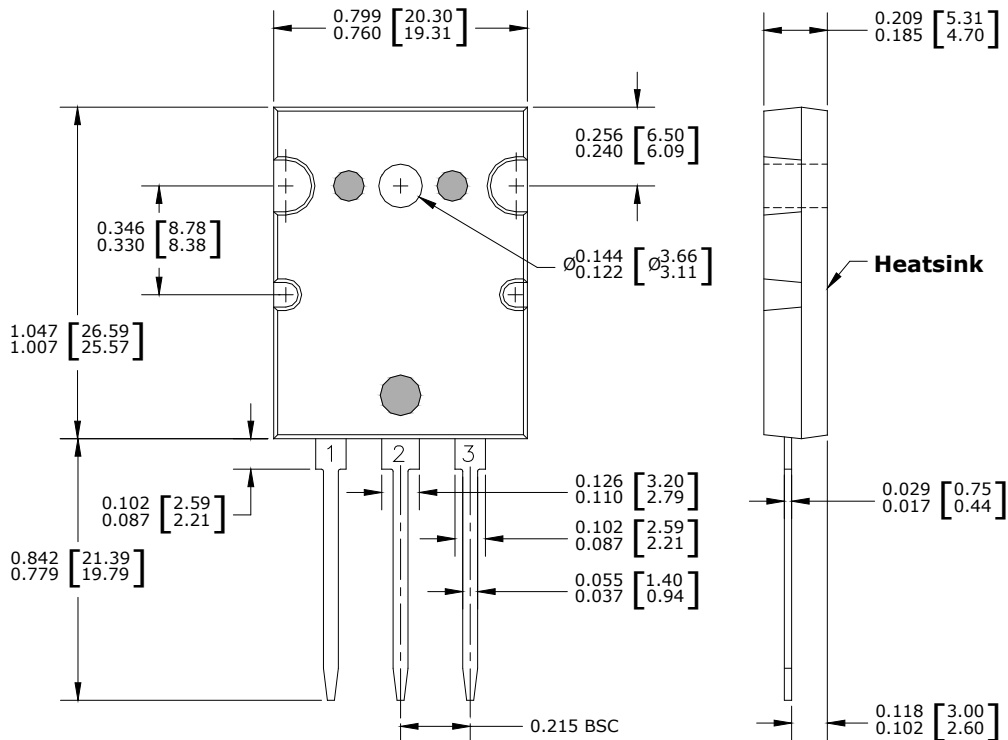
Drain-Source Diode Characteristics and Maximum Ratings

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Drain-source diode forward voltage	V_{SD}	$V_{GS} = 0V, I_F = 52A$	-	0.8	1.2	V
Reverse recovery time	t_{rr}	$V_R = 400V, I_S = I_F = 26A,$ $di_F/dt = 100A/\mu s$	-	920	-	ns
Reverse recovery charge	Q_{rr}		-	30	-	μC
Peak reverse recovery current	I_{rrm}		-	65	-	A

Notes:

1. Pulse width t_p limited by T_{jmax}
2. Repetitive avalanche causes additional power losses than can be calculated as $P_{AV} = E_{AR} * f$.

Package Outline Drawing



CoolMOS™ is a registered trademark of Infineon Technologies

CAUTION: These devices are ESD sensitive. Use proper handling procedure.

Disclaimer

These specifications may not be considered as a guarantee of components characteristics. Components have to be tested depending on intended application as adjustments may be necessary. The use of **iQXPRZ Power Inc.** components in life support appliances and systems are subject to written approval of **iQXPRZ Power Inc.**